

### General Description

The **MPD8021** is a semicustom, high-voltage, mixed-mode, power ASIC (Application Specific Integrated Circuit) suitable for quantities from 10 to 100,000's of pieces. Clients can begin designing proprietary ASICs using a low-cost SPICE simulator and the free MPD8021 Design Kit—available for downloading via the Internet.

### Technology

The MPD8021 features bipolar/CMOS/DMOS high-voltage technology and is fabricated using Micrel's proprietary BCD5 process to combine high-speed, low-voltage digital and analog circuits with high-voltage DMOS power drive circuits on a single chip.

All logic and analog circuitry is powered from a single +3V to +12V supply. The high-voltage portion functions at voltages from +20V to over +100V and includes a charge pump.

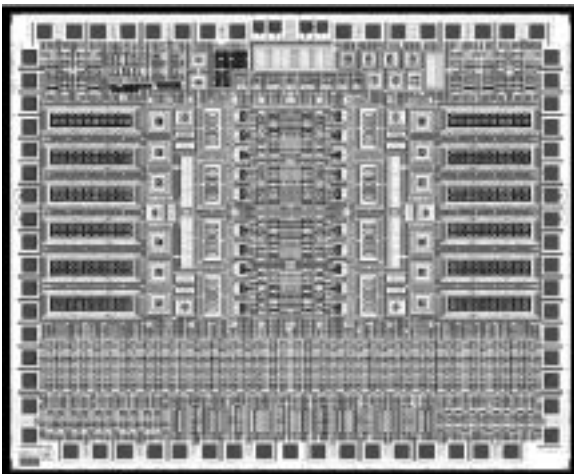
### Rapid Turnaround

Micrel delivers rapid turnaround by applying a unique metal interconnect pattern, based on the client's design, to a stock MPD8021 wafer. *To facilitate a rapid and low-cost design approach, Micrel offers MPD8021 development programs that range from limited assistance to full turnkey.*

When you are ready for production, count on Micrel's proven fab and test group to provide timely deliveries of high-quality, fully-tested, proprietary ICs.

### Low-Cost Development

There is no cost or obligation to begin developing your own MPD8021-based custom IC. "Kit parts" which are actual working designs, featuring access to many internal functions, are available for breadboarding circuits.



MPD8021 Die (0.192" × 0.200")

### Features

- 12 N-channel, 100V, 200mA, 10Ω, fully-floating DMOS power FETs (can be paralleled for 100V, 2.4A, 0.83Ω single, half-bridge, or bilateral switches)
- 40 high-voltage PMOS FETs (for level shifting, high-voltage amplifiers)
- 12 high-voltage 200Ω, DMOS FETs (for level shifting, voltage amplifiers)
- 20 high-voltage, grounded-source, DMOS FETs (for level shifting, current mirrors)
- >100 uncommitted CMOS gates
- 12 CMOS/TTL I/O buffers
- 13 low-voltage CMOS tile arrays (for op amps, comparators, digital circuitry)
- 14 dual-collector PNPs and 12 NPNs (for trimmed bandgaps, low-offset amplifiers or comparators, temperature sensor)
- 3-bit trimming network (for production trimmed bandgaps or offsets)
- High- and low-value resistors and capacitors (>1MΩ total resistance, 45pF total capacitance)
- 12V and 6V zener diodes (gate-to-source clamps, voltage references)
- 67 I/O pads (36 include 2kV ESD protection)
- Guaranteed -55°C to +150°C operation
- Several package options
- Low-cost prototyping program
- Design support via Internet

### Applications

- 2φ and 3φ motor control
- High-voltage, controlled-slew, bus drivers
- High-voltage display drivers
- Lamp drivers with current limit and overtemperature protection
- Relay and solenoid drivers
- Half- and full-bridge drivers
- Multioutput switching power supplies
- High-voltage linear power supplies
- High-voltage signal processing

### MPD8021 World-Wide Web Site

- <http://www.micrel.com>  
— select "EZANALOG" or "Custom Solutions"
- e-mail: [help@ezanalog.com](mailto:help@ezanalog.com)

## Ordering Information

Part Number	Type	Temperature Range	Package
MIC8021-xxxx*	custom	-55°C to +125°C	customer specified
MIC8021-0001	kit part	-55°C to +125°C	68-pin PLCC
MIC8021-0002	kit part	-55°C to +125°C	68-pin PLCC

\* custom part number. Package markings customer specified.

### MPD8021-0001 Kit Part High-Voltage PWM Controller†

High-voltage push-pull output stages ..... 6 with CMOS to high-voltage level shifters and crossover protection logic	
High-voltage charge pump for high-side drive with integral high-side current mirror	
Bandgap reference ..... 1 with PTAT voltage output (usable for thermal shutdown)	
Op amp ..... 1	
Comparators ..... 4	
Floating logic input	
Undervoltage lockout	

† Digital cells and miscellaneous components are not accessible from the pins of this device.

### MPD8021-0002 Kit Part High-Voltage Characterization Array‡

High-voltage NPN transistors ..... 4 (includes matching pair)	
High-voltage PNP transistor ..... 1	
High-voltage P-channel FETs ..... 2	
Analog and digital low-voltage MOSFETs ..... 8	
Expitaxial JFET ..... 1	
200Ω and 10Ω high-voltage DMOS transistors ..... 3	
6V and 12V Zener diodes ..... 2	
Small Schottky diode ..... 1	
ESD input protection structures ..... 2	
High-value resistor (100k) ..... 1	
Low-value resistor (7.6k) ..... 1	
Low-value polysilicon resistor ..... 1	

‡ This device is suitable for curve tracer or bench-top characterization of various device types included in the MPD8021 array. This device is a supplement to the design information available in the Internet Design Kit.

## Absolute Maximum Ratings

DC Input Voltage Negative, Any Pin ( $V_{IL}$ ), <b>Note 1</b> ..... $V_{SUB} - 0.5V$	
DC Input Voltage Positive ESD Pin ( $V_{IH}$ ), <b>Note 2</b> ..... $V^+ + 0.5V$	
Low-Voltage Supply Differential, <b>Note 3</b> ..... +16.5V	
DMOS Output Device Breakdown ( $BV_{DSS}$ ), <b>Note 4</b> ..... +110V	
DMOS Drain Current Continuous ( $I_{D(max)}$ ), <b>Note 5</b> ..... 0.2A Pulsed ( $I_{D(pulse)}$ ), <b>Note 6</b> ..... 0.5A	
DMOS Gate Drive Voltage ( $V_{GS(max)}$ ), <b>Note 7</b> ..... ±20V	
Standard ESD Structure Voltage ( $V_{ESD}$ ), <b>Note 8</b> ..... 2kV	
Storage Temperature ( $T_S$ ) ..... -65°C to +150°C	

**General Note:** Devices are ESD protected; however, handling precautions are recommended.

**Note 1:**  $V_{SUB}$  is the substrate bias voltage.

**Note 2:**  $V^+$  is the positive ESD clamp potential, user specified up to +100V.

**Note 3:** Maximum voltage across low-voltage analog or digital MOS.

**Note 4:** DMOS source-to-body shorted to substrate at 0V.

**Note 5:**  $V_{GS} = 15V$ .

**Note 6:** 5μs pulse, 10% duty cycle.

**Note 7:** Measured relative to source-to-body short.

**Note 8:** Measured between any two pins.

## Operating Ratings

Ambient Temperature ( $T_A$ ) ..... -55°C to +125°C
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## Electrical and Physical Summary

Bonding Pads ..... 67	
2kV ESD Pads ..... 36	
Die Size ..... 0.222 in. × 0.182 in.	
CMOS Output Buffer Tiles ..... 12	
CMOS Analog Tiles ..... 13	
High-Power DMOS ..... 12@10Ω	
Bipolar Devices	
split-collector PNP ..... 14	
NPN ..... 14	
zener diodes ..... 10	
CMOS Logic Devices	
NMOS ..... 354	
PMOS ..... 354	
Resistance	
P-well ..... 1MΩ	
N+ ..... 20kΩ	
polysilicon ..... up to 50kΩ	
Capacitance ..... 45pF	
Trimming Range ..... 3 bits	